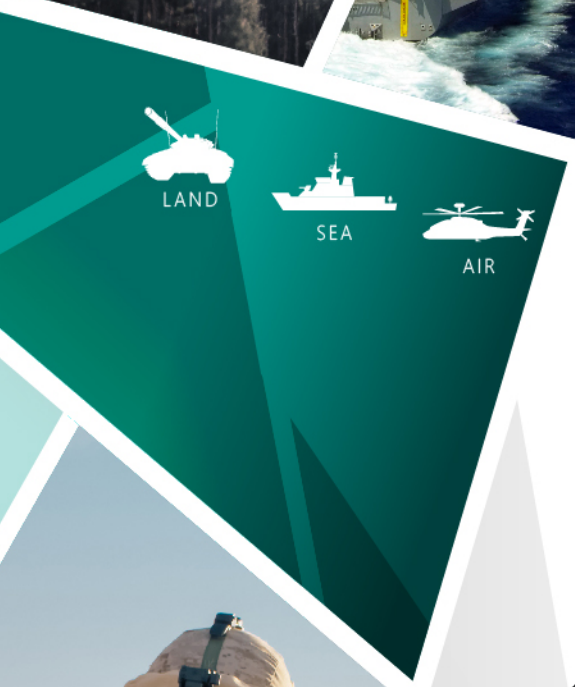


7SL-XR7620

Intel 4/5th XEON SP 2U, 2-socket Short-depth Military Rugged HPC

- Two Intel® 4th /5th Xeon Scalable Processor CPUs with up to 32 Cores
- 16 DDR5 DIMM slots, supports RDIMM 1 TB max, speeds up to 5600 MT/s. Supports registered ECC DDR5 DIMMs only
- Front bays: Up to 4 x 2.5-inch SATA III, SAS, or NVMe SSDs max 61.44 TB, up to 8 x E3.S NVMe direct drives, 51.2TB max
- Cryptographically signed firmware, Secure Boot, TPM 2.0 FIPS, CC-TCG certified
- 2x 10G LAN,1x RJ45 1GbE LAN ,1x USB 3.0, 1x USB2.0,1x Mini-DP
- Up to 5 PCIe slots (4 x16 Gen4/Gen5, 1 x 16 LP Gen4)
- Redundant 1800W Platinum power supply support 100V-240V, 240V HVDC support 1+1 active-active support hot plug
- Embedded Management: iDRAG Direct, iDRAC RESTful API with Redfish iDRAC Service
- Lightweight aluminum chassis with stainless steel reinforcement
- Electrical interference input filtering and cable shielding
- Conformal coating (Options)
- Design to meet MIL-STD-461/MIL-STD-810

Product Highlight

Technical Specification

5th/4th Gen Intel® Xeon® Scalable processors, Two Socket LGA-4677 (Socket E)
Up to 16/32 Cores per Processor
Up to 1TB memory with 16 DIMM slots
Storage Internal Controllers: PERC H965i, PERC H965e, PERC H755, PERC H355, HBA355i
(BOSS-N1): HWRAID 1, 2 x M.2 NVMe SSDs

Management and Operating System

Windows®, VMWARE, Ubuntu Server LTS, Windows Server with Hyper-V, Red Hat Enterprise Linux, SUSE Linux Enterprise Server, VMware ESX
AMI UEFI BIOS type
iDRAC9, iDRAC Direct, iDRAC RESTful API with Redfish, iDRAC Service Module, NativeEdge Endpoint Orchestrator
TPM 2.0 support

Expansion

Up to 5 PCIe slots (4 x16 Gen4/Gen5, 1 x 16 LP Gen4)
4x 2.5-inch SATA III, SAS, or NVMe SSDs max 61.44 TB, Up to 8 x E3.S NVMe direct drives, 51.2TB max

Input/Output Versatility

1x Power Button
1x SSD Status LED
2x AC-IN Jack
(Front)
1x iDRAC Direct (Micro-AB USB 2.0) port, 1 x USB 2.0
(Rear)
1 x iDRAC dedicated port, 1 x USB 3.0, 1 x Serial (Micro- AB USB 2.0) port, 1 x Mini-DisplayPort, 1 x RJ45 for dry contact, 2 x 10 GbE

Power Supply Options

Redundant 1800 W Platinum 100/240V VAC
1100 W 48 V~ (60) VDC (Optional)

Thermal Solution

Air Cooling 6 x Standard cold swap fans

Environmental

Operating

Temperature: -10°C to 55°C
Humidity: 5%to 95%, non-condensing
Shock: 3 axis, 25g
Vibration: 5Grms

Non-Operating

Temperature: -20°C to 60°C
Humidity: 5%to 95%, non-condensing

MIL-STD-810 Test

Method 500.5, Procedures I and II (Altitude, Operation): 12,192M, (40,000 ft) for the initial cabin altitude (18.8Kpa or 2.73 Psia)
Method 500.5, Procedures III and IV (Altitude, Non-Operation):
15,240, (50,000 ft) for the initial cabin altitude (14.9Kpa or 2.16 Psia)
Method 501.5, Procedure I (Storage/High Temperature)
Method 501.5, Procedure II (Operation/High Temperature)
Method 502.5, Procedure I (Storage/Low Temperature)
Method 502.5, Procedure II (Operation/Low Temperature)
Method 503.5, Procedure I (Temperature shock)
Method 507.5, Procedure II (Temperature & Humidity)
Method 509.7 Salt Spray (50±5)g/L(Optional for Conformal Coating)
Method 514.6, Vibration Category 24/Non-Operating (Category 20 & 24, Vibration)
Method 514.6, Vibration Category 20/Operating (Category 20 & 24, Vibration)
Method 516.6, Shock-Procedure V Non-Operating (Mechanical Shock)
Method 516.6, Shock-Procedure I Operating (Mechanical Shock)

Mechanical

Height: 3.41 inches (86.8mm)
Width: 19 inches (482.6mm)
Depth: 22 inches (572mm) with bezel
18.57inches (471.8mm) without bezel
Weight: 46.64 pounds (21.16kg)

Specifications

System

Processor	**Two 5th Gen Intel® Xeon® / 4th Gen Intel® Xeon® Scalable processors, Socket E (LGA-4677)**
CPU Core Count	**Up to 16Cores/32Cores**
Memory type	**DDR5-5600MT/s RDIMM ECC, up to 1TB in 8 DIMM slot**
GPU Options	**Up to 5 x 75W (Single Width Full Height/Half Length, Low Profile) GPU or Up to 2 x 300W (Double Width Full Height/Full Length)**
TPM	**Chipset: Infineon, Type: TPM 2.0**
IPMI	**iDRAC RESTful API with Redfish**
BIOS	**AMI UEFI BIOS**
USB	**1x USB3.0 +1x USB2.0 ports**
Ethernet	**4x 25G Ethernet SFP+ Ports**
Power Type	**100V~240V AC IN Redundant**
Storage	**4x 2.5" Swappable SATA SAS, or NVMe SSD or 8 x E3.S NVMe direct drives**
Operating Temp.	**-10°C to +55°C**
Dimension	**482mm(W) x 572mm(D)x86mm(H)**

Front I/O

Power Button	**1x**
SSD LED indicator	**1x**
Swappable SSD Tray	**4x**
iDRAC	**1x iDRAC Direct (Micro-AB USB 2.0) port, 1 x USB 2.0**

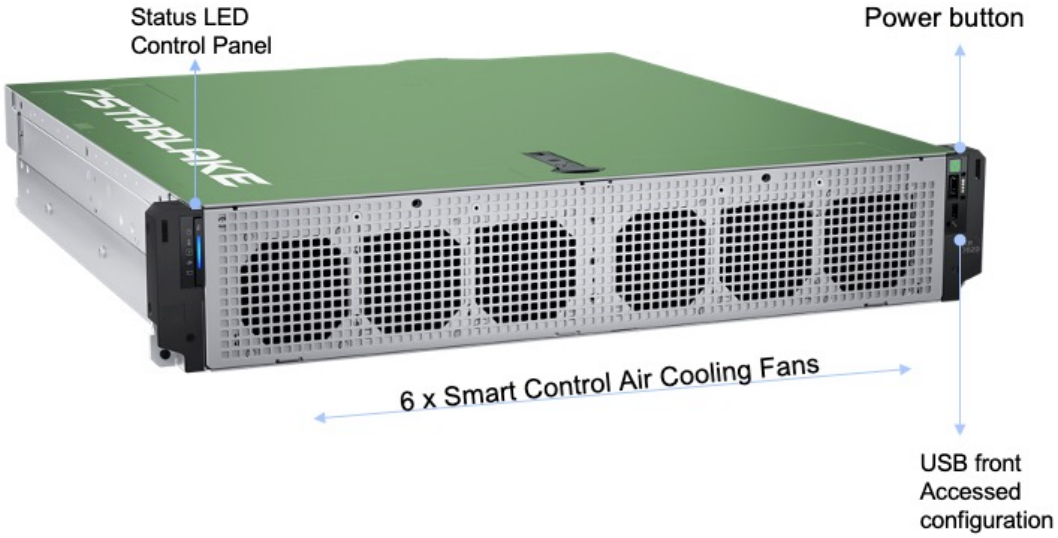
Rear I/O

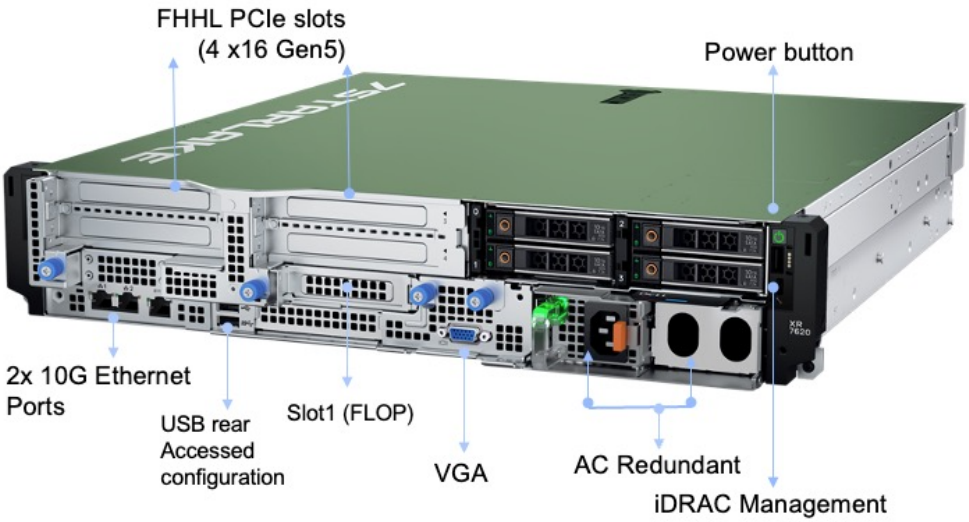
iDRAC	**1x iDRAC dedicated Direct port**
USB3.0	**1x**
Serial	**1 x (Micro-AB USB 2.0)**
1G LAN	**1x**
10 LAN	**2x**
Display port	**1x Mini-DP or VGA**

Environmental

MIL-STD-810 Test	Method 500.5, Procedures I and II (Altitude, Operation): 12,192M, (40,000 ft) for the initial cabin altitude (18.8Kpa or 2.73 Psia) Method 500.5, Procedures III and IV (Altitude, Non-Operation): 15,240, (50,000 ft) for the initial cabin altitude (14.9Kpa or 2.16 Psia) Method 501.5, Procedure I (Storage/High Temperature) Method 501.5, Procedure II (Operation/High Temperature) Method 502.5, Procedure I (Storage/Low Temperature) Method 502.5, Procedure II (Operation/Low Temperature) Method 503.5, Procedure I (Temperature shock) Method 507.5, Procedure II (Temperature & Humidity) Method 509.7 Salt Spray (50±5)g/L(Optional for Conformal Coating) Method 514.6, Vibration Category 24/Non-Operating (Category 20 & 24,Vibration) Method 514.6, Vibration Category 20/Operating (Category 20 & 24,Vibration) Method 516.6, Shock-Procedure V Non-Operating (Mechanical Shock) Method 516.6, Shock-Procedure I Operating (Mechanical Shock)
Operating Temp	-10°C to +55°C
Storage Temp.	-20°C to +60°C
Relative Humidity	5% to 95%, non-condensing.

Appearance


Status LED
Control Panel
Power button
6 x Smart Control Air Cooling Fans
USB front
Accessed
configuration


FHHL PCIe slots
(4 x16 Gen5)
Power button
2x 10G Ethernet
Ports
USB rear
Accessed
configuration
Slot1 (FLOP)
VGA
AC Redundant
iDRAC Management

Ordering Information

	7SL-XR7620-AC	7SL-XR7620-DC
CPU	Two 5th Gen Intel® Xeon® / 4th Gen Intel® Xeon® Scalable processors, Socket E (LGA-4677)	Two 5th Gen Intel® Xeon® / 4th Gen Intel® Xeon® Scalable processors, Socket E (LGA-4677)
RAM	DDR5-5600MT/s RDIMM ECC, up to 1TB in 16 DIMM slot	DDR5-5600MT/s RDIMM ECC, up to 1TB in 16 DIMM slot
Storage	4x 2.5" Swappable SATA SAS, or NVMe SSD or 8 x E3.S NVMe direct drive	4x 2.5" Swappable SATA SAS, or NVMe SSD or 8 x E3.S NVMe direct drive
Power	1800W 100V~240V AC IN Redundant	1100W DC 48V~60V
Thermal	Active Smart Fan Cooling	Active Smart Fan Cooling